

IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A member for a circuit board, comprising:
an electrically insulating material; and
a mold release film that is provided on at ~~least~~least one side of the electrically insulating material,
wherein the mold release film contains or is coated with a heat absorbing substance having a heat absorbing property.
2. (Original) The member according to claim 1,
wherein the heat absorbing substance is a metal hydrate.
3. (Original) The member according to claim 2,
wherein the metal hydrate is at least one selected from the group consisting of: aluminum hydroxide, magnesium hydroxide, dawsonite, potassium aluminate, calcium hydroxide, zinc borate, kaolin clay, and calcium carbonate.
4. (Original) The member according to claim 1,
wherein the mold release film is formed of a film of a thermoplastic resin or a thermosetting resin.
5. (Original) The member according to claim 4,
wherein the thermoplastic resin is at least one selected from the group consisting of: polyethylene naphthalate, polyphenylene sulfite, polyethylene terephthalate, polypropylene, and polyphenylene oxide.

6. (Original) The member according to claim 4,
wherein the thermosetting resin is at least one selected from the group consisting of: epoxy resin, phenol resin, polyimide resin, polyester resin, silicone resin, and melamine resin.
7. (Original) The member according to claim 1,
wherein a layer containing a thermosetting resin further is provided in the mold release film.
8. (Original) The member according to claim 7,
wherein the thermosetting resin layer of the mold release film contains a heat absorbing substance.
9. (Original) The member according to claim 8,
wherein the heat absorbing substance contained in the thermosetting resin layer of the mold release film is at least one selected from the group consisting of: aluminum hydroxide, magnesium hydroxide, dawsonite, potassium aluminate, calcium hydroxide, zinc borate, kaolin clay, and calcium carbonate.
10. (Original) The member according to claim 1,
wherein the mold release film further includes a resin layer containing a heat absorbing substance as well as a thermosetting resin layer and a film layer.
11. (Original) The member according to claim 10,
wherein the resin layer containing the heat absorbing substance is formed from at least one type of metal hydrate selected from the group consisting of: aluminum hydroxide, magnesium hydroxide, dawsonite, potassium aluminate, calcium hydroxide, zinc borate, kaolin clay, and calcium carbonate.
12. (Original) The member according to claim 1,

wherein the electrically insulating material is formed of a composite material of a woven fabric or a nonwoven fabric containing organic fibers or inorganic fibers as a main component and a thermosetting resin that is impregnated into the woven fabric or the nonwoven fabric and brought to a semi-cured state.

13. (Original) The member according to claim 12,
wherein the composite material contains an inorganic filler.
14. (Original) The member according to claim 1,
wherein an endothermic temperature of the heat absorbing substance is not lower than a softening point of a thermosetting resin impregnated into the insulating material.
15. (Original) The member according to claim 1,
wherein a heat absorbing substance having a heat absorbing property is present in an amount of more than 0 mass % to not more than 60 mass % with respect to the mold release film.
16. (Original) The member according to claim 8,
wherein a metal hydrate in an amount in a range of more than 0 mass % to 95 mass % is mixed into the thermosetting resin.
17. (Withdrawn) A method of manufacturing a member for a circuit board,
comprising:
allowing a mold release film to adhere to at least one side of a composite material (hereinafter, referred to as a prepreg) by heating and pressing, the prepreg being formed of an electrically insulating material made of a core material and a thermosetting resin that is impregnated into the core material and brought to a semi-cured state, the mold release film containing or being coated with a heat absorbing substance having a heat absorbing property,

wherein the heating is performed at a temperature not lower than a softening point of the prepreg and not higher than an endothermic temperature of the heat absorbing substance.

18. (Withdrawn) A method of manufacturing a circuit board, comprising:
laminating a mold release film on at least one side of a composite material (hereinafter, referred to as a prepreg), the prepreg being formed of an electrically insulating material made of a core material and a thermosetting resin that is impregnated into the core material and brought to a semi-cured state, the mold release film containing or being coated with a heat absorbing substance having a heat absorbing property;
forming through-holes in predetermined positions in a member for a circuit board using a laser, the member being obtained by allowing the mold release film to adhere to the prepreg by heating and pressing at a temperature not lower than a softening point of the prepreg and not higher than an endothermic temperature of the heat absorbing substance;
filling the through-holes with a conductive paste;
taking out the prepreg by peeling the mold release film off of the member in which the conductive paste is filled;
placing metal foil on each surface of the prepreg and subsequently performing heating and pressing so that a laminate is formed by thermocompression bonding; and
forming a circuit pattern on the laminate so as to obtain a double-sided circuit board.

19. (Withdrawn) The method according to claim 18,
wherein process steps of forming the laminate and forming the circuit pattern on a surface of the laminate are performed at least twice repeatedly so as to obtain a multilayer circuit board.

20. (Withdrawn) A method of manufacturing a circuit board, comprising:
laminating a mold release film on at least one side of a composite material (hereinafter, referred to as a prepreg), the prepreg being formed of an electrically

insulating material made of a core material and a thermosetting resin that is impregnated into the core material and brought to a semi-cured state, the mold release film containing or being coated with a heat absorbing substance having a heat absorbing property;

forming through-holes in predetermined positions in a member for a circuit board using a laser, the member being obtained by allowing the mold release film to adhere to the prepreg by heating and pressing at a temperature not lower than a softening point of the prepreg and not higher than an endothermic temperature of the heat absorbing substance;

filling the through-holes with a conductive paste;

taking out the prepreg by peeling the mold release film off of the member in which the conductive paste is filled;

separately preparing at least two circuit boards that have at least two circuit patterns;

alternately arranging the circuit boards and a number of the prepregs, the number of the prepregs exceeding a number of the circuit boards by one;

further placing metal foil in an outermost position and subsequently performing heating and pressing so that a laminate is formed; and

forming a circuit pattern on the laminate so as to obtain a multilayer circuit board.